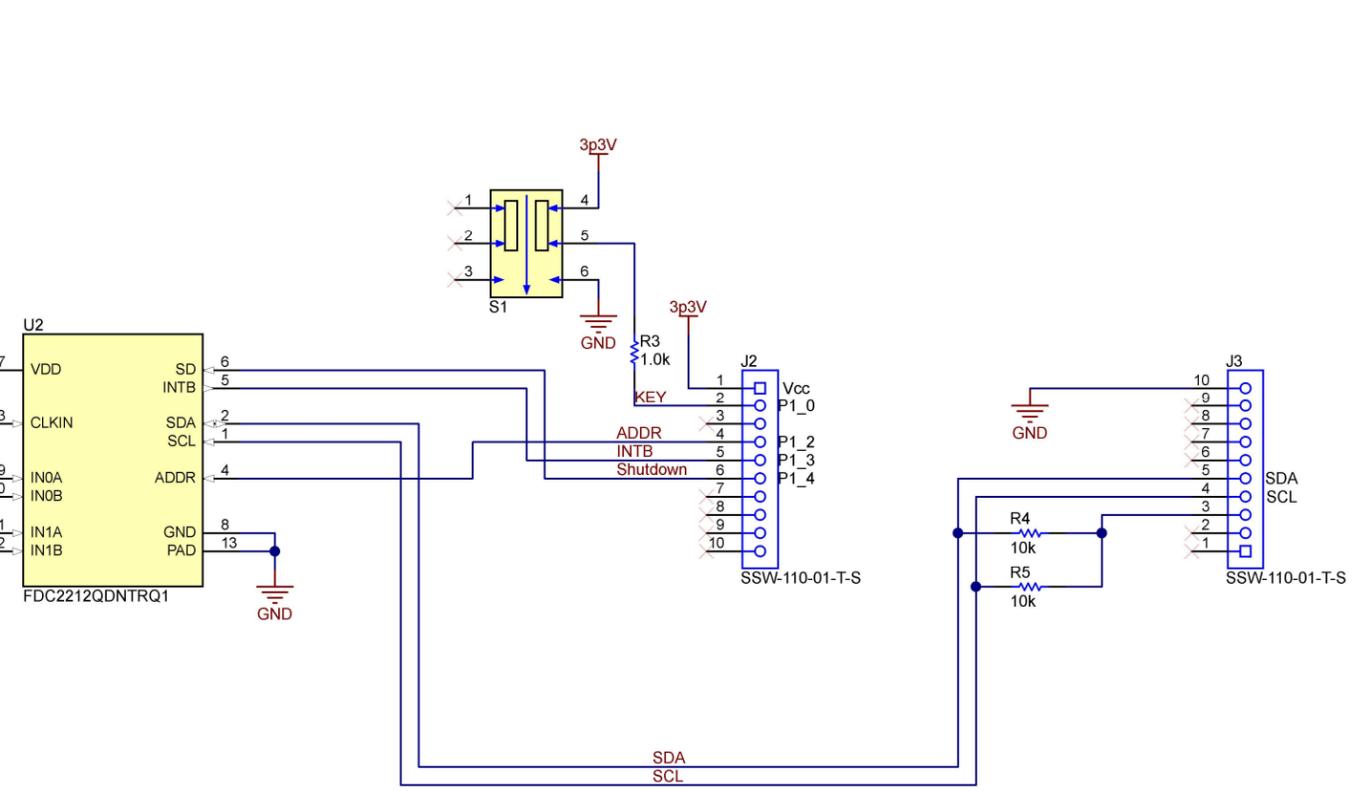


Resonant frequency of this R and C is about 6 MHz



Orderable: N/A	Designed for: Public Release	Mod. Date: 6/29/2017
TID #: 01409	Project Title: Automotive Kick-to-Open Capacitive	
Number: TIDA-01409	Rev: E2	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: TIDA_01409_Schematic2.SchDoc	Size: B
Engineer: C.Kinnaid	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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